



# Z-COAT 100

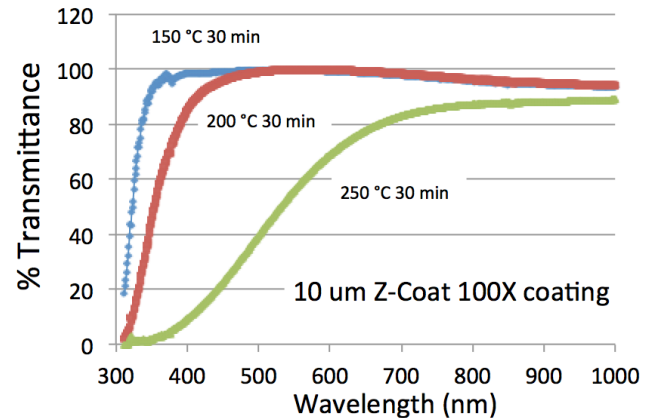
## Wafer Surface/Bump Protection Film (Water Soluble)

Z-Coat 100 is a spin-on coating designed for wafer surface and bump temporary protection in laser dicing/drilling and process handling. Z-Coat 100 can be easily removed with DI water at room temperature.

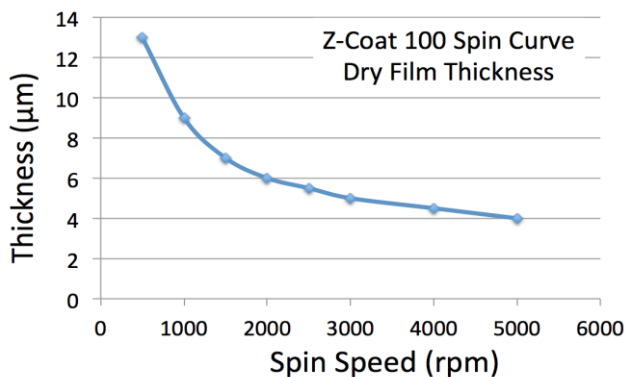
### Basic Material Property

Z-COAT 100	
Appearance	Clear/Light Yellow
Odor	Slight
Viscosity	400~500 cps
Solvent	Di-water with IPA
Thermal	Stable Up to 280°C, Optical Clear to 200°C
Coating	Spin Coating
Package	Available in 1kg and 1 gallon bottle
Storage	Room Temperature

### Transparency:



### Spin Coating

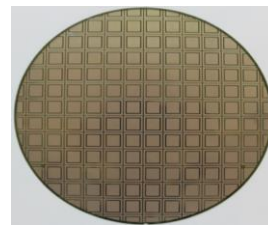


For laser dicing application, the recommended Z-Coat 100 thickness is < 5 µm.

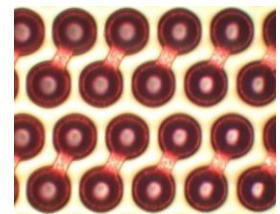
### Drying:

Thickness	Recommended Dry Condition
< 5 µm	60 °C 5 minutes + 120°C 2 minutes
5 ~ 10 µm	60 °C 5 minutes + 120°C 5 minutes
> 10 µm	60 °C 5 minutes + 120°C 10 minutes

Slower than 500 rpm spin speed coating is NOT recommended.



Bumped wafer



bumps under hi-mag  
5 µm Z-Coat 100 on bumped wafer after dry

### Other Properties:

- Decomposition at 390 °C
- Optically clear after 200 °C 30 minutes bake
- No corrosion-Metal Safe-Environmental Friendly.

### Cleaning:

Z-Coat 100X can be easily removed with DI-water. For best cleaning result, use warm DI water (~70 °C) to rinse or soak, followed by spin dry.

### Contact:

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